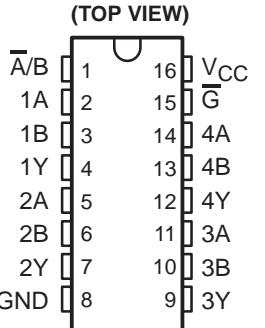


SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
WITH 3-STATE OUTPUTS

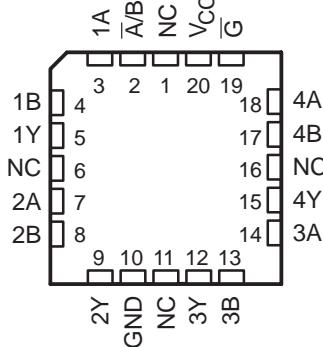
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Inverting Outputs Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- 'HC257 . . . Typical $t_{pd} = 9$ ns
- 'HC258 . . . Typical $t_{pd} = 12$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Provides Bus Interface from Multiple Sources in High-Performance Systems

SN54HC257, SN54HC258 . . . J PACKAGE
SN74HC257, SN74HC258 . . . D, N, NS, OR PW PACKAGE



SN54HC257, SN54HC258 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC257N	SN74HC257N
			SN74HC258N	SN74HC258N
	SOIC – D	Tube of 40	SN74HC257D	HC257
			SN74HC257DR	
		Reel of 2500	SN74HC257DT	
			SN74HC258D	
			SN74HC258DR	
	SOP – NS	Reel of 2000	SN74HC257NSR	HC257
			SN74HC258NSR	HC258
	TSSOP – PW	Tube of 90	SN74HC257PW	HC257
			SN74HC257PWR	
			SN74HC257PWT	
		Reel of 2000	SN74HC258PW	HC258
			SN74HC258PWR	
		Reel of 250	SN74HC258PWT	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC257J	SNJ54HC257J
			SNJ54HC258J	SNJ54HC258J
	LCCC – FK	Tube of 55	SNJ54HC257FK	SNJ54HC257FK
			SNJ54HC258FK	SNJ54HC258FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS INSTRUMENTS

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
WITH 3-STATE OUTPUTS

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description/ordering information (continued)

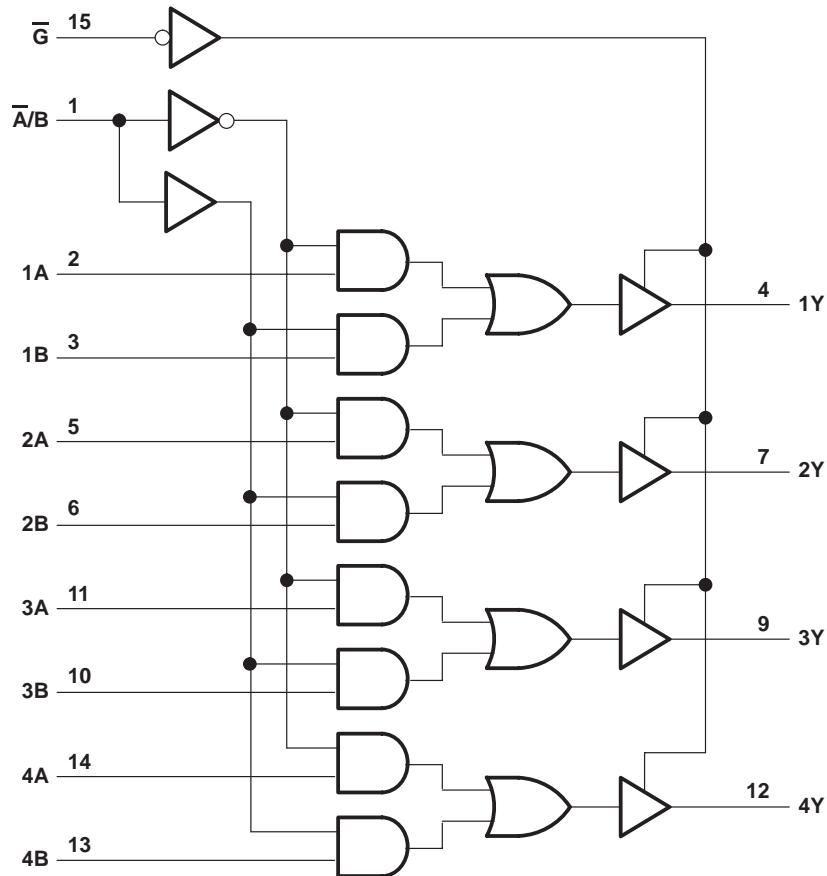
These devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\bar{G}) input is at a high logic level.

To ensure the high-impedance state during power up or power down, \bar{G} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

\bar{G}	INPUTS		OUTPUT Y		
	\bar{A}/B	A	B	'HC257	'HC258
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

'HC257 logic diagram (positive logic)

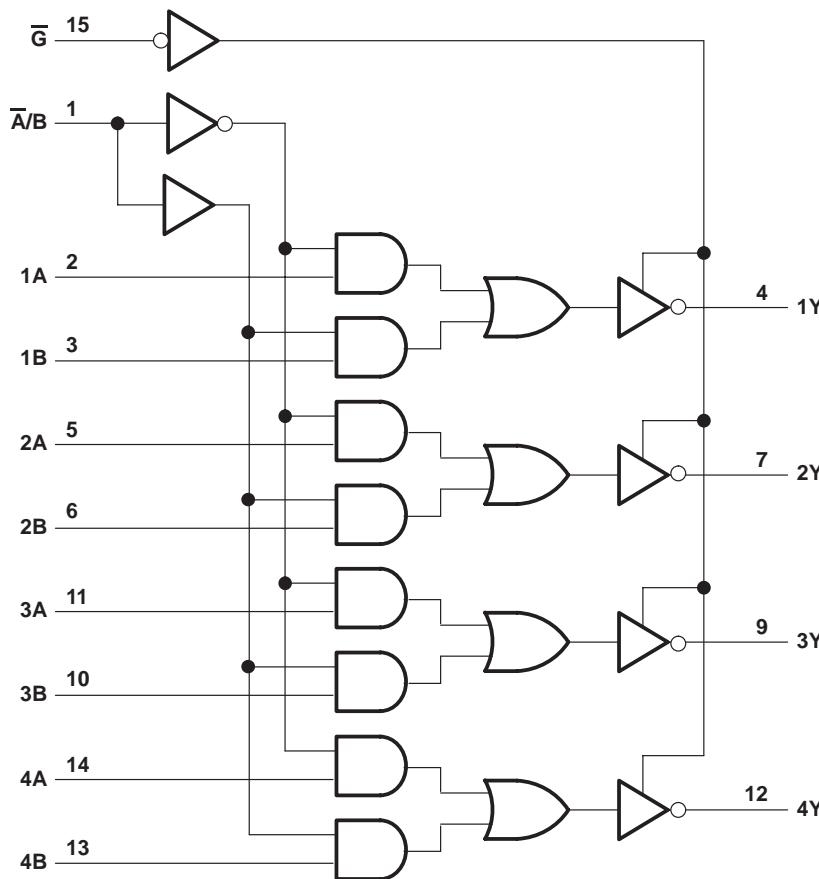


Pin numbers shown are for the D, J, N, NS, and PW packages.

SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
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'HC258 logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and PW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 35 mA
Continuous current through V_{CC} or GND	± 70 mA
Package thermal impedance, θ_{JA} (see Note 1):	
D package	73°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
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recommended operating conditions (see Note 2)

			SN54HC257, SN54HC258			SN74HC257, SN74HC258			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC}	Supply voltage			2	5	6	2	5	6	V
V _{IH}	High-level input voltage			V _{CC} = 2 V	1.5		1.5			V
				V _{CC} = 4.5 V	3.15		3.15			
				V _{CC} = 6 V	4.2		4.2			
V _{IL}	Low-level input voltage			V _{CC} = 2 V		0.3		0.5		V
				V _{CC} = 4.5 V		0.9		1.35		
				V _{CC} = 6 V		1.2		1.8		
V _I	Input voltage			0	V _{CC}	0	V _{CC}	0	V _{CC}	V
V _O	Output voltage			0	V _{CC}	0	V _{CC}	0	V _{CC}	V
Δt/Δv	Input transition rise/fall time			V _{CC} = 2 V		1000		1000		ns
				V _{CC} = 4.5 V		500		500		
				V _{CC} = 6 V		400		400		
T _A	Operating free-air temperature			-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC257, SN54HC258		SN74HC257, SN74HC258	UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998	1.9		1.9	V
			4.5 V	4.4	4.499	4.4		4.4	
			6 V	5.9	5.999	5.9		5.9	
		I _{OH} = -6 mA	4.5 V	3.98	4.3	3.7		3.84	
		I _{OH} = -7.8 mA	6 V	5.48	5.8	5.2		5.34	
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V	0.002	0.1	0.1		0.1	V
			4.5 V	0.001	0.1	0.1		0.1	
			6 V	0.001	0.1	0.1		0.1	
		I _{OL} = 6 mA	4.5 V	0.17	0.26	0.4		0.33	
		I _{OL} = 7.8 mA	6 V	0.15	0.26	0.4		0.33	
I _I	V _I = V _{CC} or 0		6 V	±0.1	±100	±1000		±1000	nA
I _{OZ}	V _O = V _{CC} or 0		6 V	±0.01	±0.5	±10		±5	μA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V		8	160		80	μA
C _i		2 V to 6 V		3	10	10		10	pF

SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC257		SN74HC257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Any Y	2 V	50	100	150	150	125	125	125	ns
			4.5 V	10	20	30	30	25	25	25	
			6 V	9	17	25	25	21	21	21	
	\overline{A}/B	Any Y	2 V	50	100	150	150	125	125	125	
			4.5 V	10	20	30	30	25	25	25	
			6 V	9	17	25	25	21	21	21	
t_{en}	\overline{G}	Any Y	2 V	75	150	225	225	190	190	190	ns
			4.5 V	15	30	45	45	38	38	38	
			6 V	13	26	38	38	32	32	32	
t_{dis}	\overline{G}	Any Y	2 V	75	150	225	225	190	190	190	ns
			4.5 V	15	30	45	45	38	38	38	
			6 V	13	26	38	38	32	32	32	
t_t		Any Y	2 V	28	60	90	90	75	75	75	ns
			4.5 V	8	12	18	18	15	15	15	
			6 V	6	10	15	15	13	13	13	

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC257		SN74HC257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Any Y	2 V	75	150	245	245	190	190	190	ns
			4.5 V	15	30	45	45	38	38	38	
			6 V	13	26	38	38	32	32	32	
	\overline{A}/B	Any Y	2 V	75	150	245	245	190	190	190	
			4.5 V	15	30	45	45	38	38	38	
			6 V	13	26	38	38	32	32	32	
t_{en}	\overline{G}	Any Y	2 V	100	200	300	300	250	250	250	ns
			4.5 V	24	40	60	60	50	50	50	
			6 V	18	34	51	51	43	43	43	
t_t		Any Y	2 V	45	210	315	315	265	265	265	ns
			4.5 V	17	42	63	63	53	53	53	
			6 V	13	36	53	53	45	45	45	

**SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
WITH 3-STATE OUTPUTS**

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC258	SN74HC258	UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Any Y	2 V	60	100	150	125		ns
			4.5 V	13	20	30	25		
			6 V	12	17	25	21		
	\overline{A}/B	Any Y	2 V	60	115	175	145		
			4.5 V	13	23	35	29		
			6 V	12	20	30	25		
t_{en}	\overline{G}	Any Y	2 V	70	150	225	190		ns
			4.5 V	15	30	45	38		
			6 V	13	26	38	32		
t_{dis}	\overline{G}	Any Y	2 V	75	150	225	190		ns
			4.5 V	15	30	45	38		
			6 V	13	26	38	32		
t_t		Any Y	2 V	28	60	90	75		ns
			4.5 V	8	12	18	15		
			6 V	6	10	15	13		

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC258	SN74HC258	UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Any Y	2 V	95	150	245	190		ns
			4.5 V	23	30	45	38		
			6 V	21	26	38	32		
	\overline{A}/B	Any Y	2 V	95	165	240	210		
			4.5 V	23	33	48	42		
			6 V	21	28	41	36		
t_{en}	\overline{G}	Any Y	2 V	100	200	300	250		ns
			4.5 V	24	40	60	50		
			6 V	18	34	51	43		
t_t		Any Y	2 V	45	210	315	265		ns
			4.5 V	17	42	63	53		
			6 V	13	36	53	45		

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per multiplexer	No load	40	pF

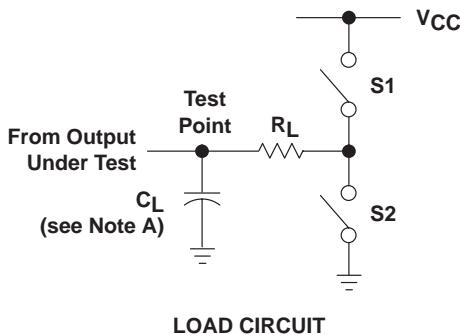


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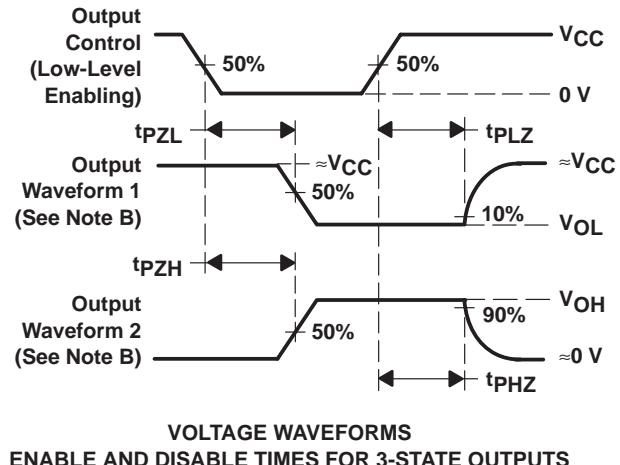
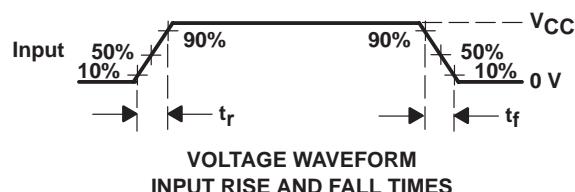
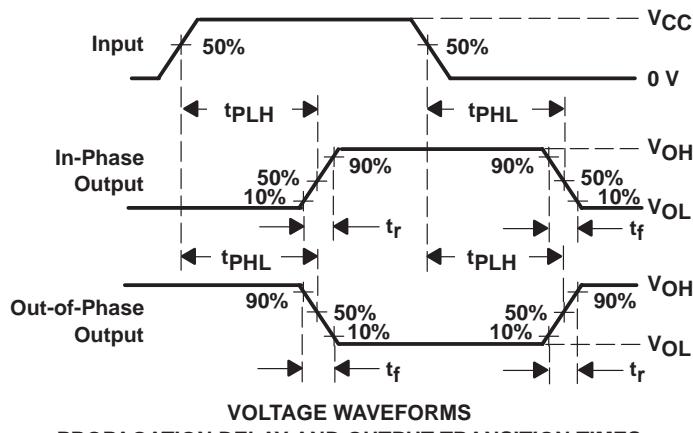
SN54HC257, SN54HC258, SN74HC257, SN74HC258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MUXES
WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



PARAMETER	R _L	C _L	S1	S2
t _{en}	1 kΩ	50 pF or 150 pF	Open	Closed
			Closed	Open
t _{dis}	1 kΩ	50 pF	Open	Closed
			Closed	Open
t _{pd} or t _t	--	50 pF or 150 pF	Open	Open



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PZL} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
85124012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8512401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54HC257J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC257NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWLE	OBsolete	TSSOP	PW	16		TBD	Call TI	Call TI
SN74HC257PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC257PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
no Sb/Br)								
SN74HC258DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC258NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC258NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC258PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC257J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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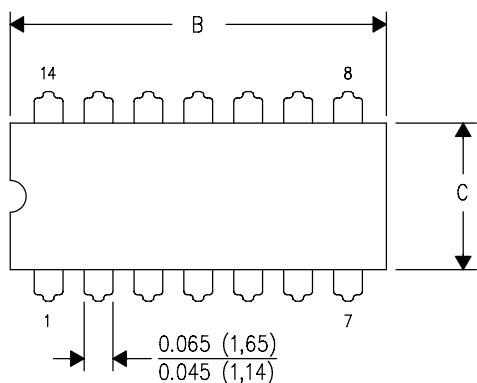
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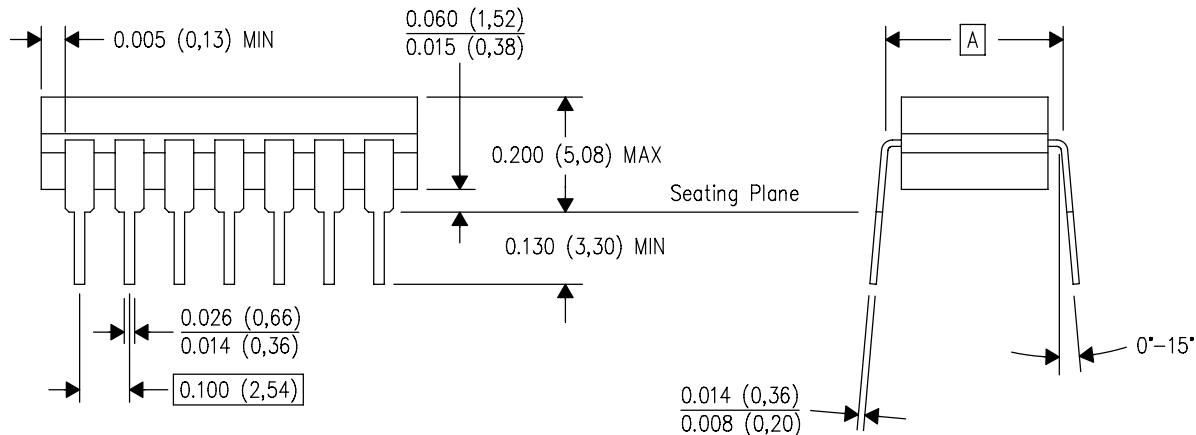
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



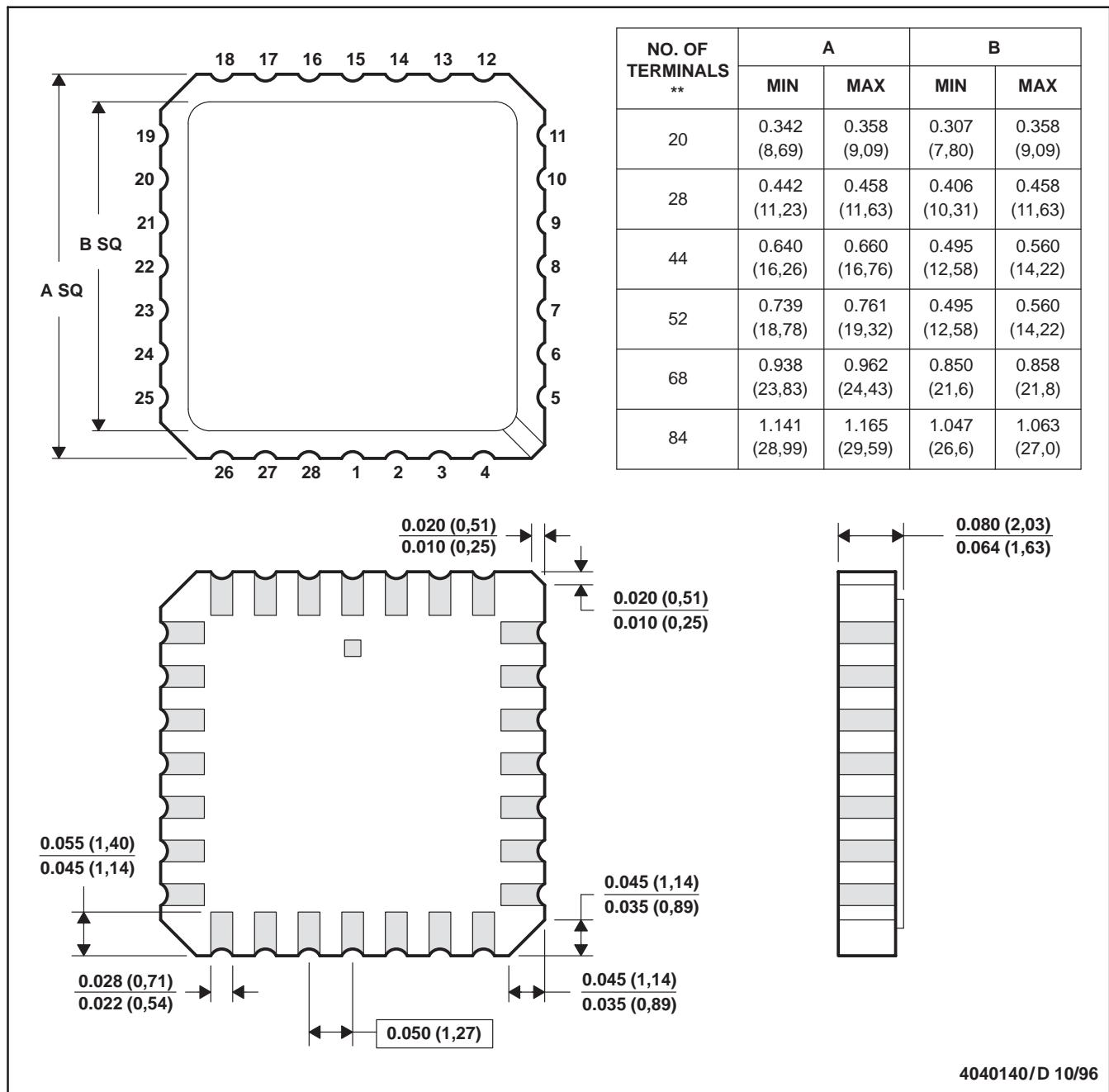
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

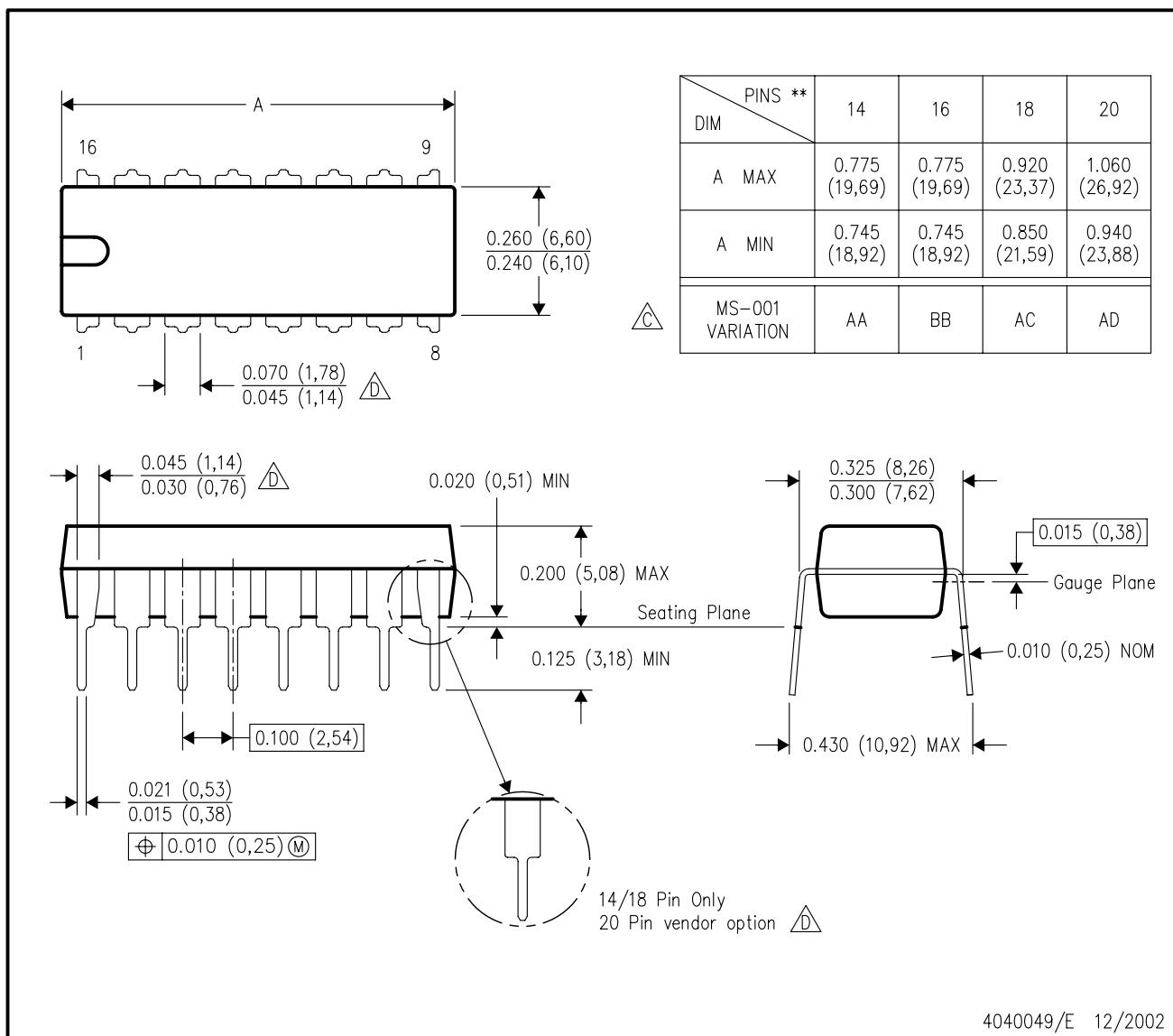
E. Falls within JEDEC MS-004

4040140/D 10/96

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



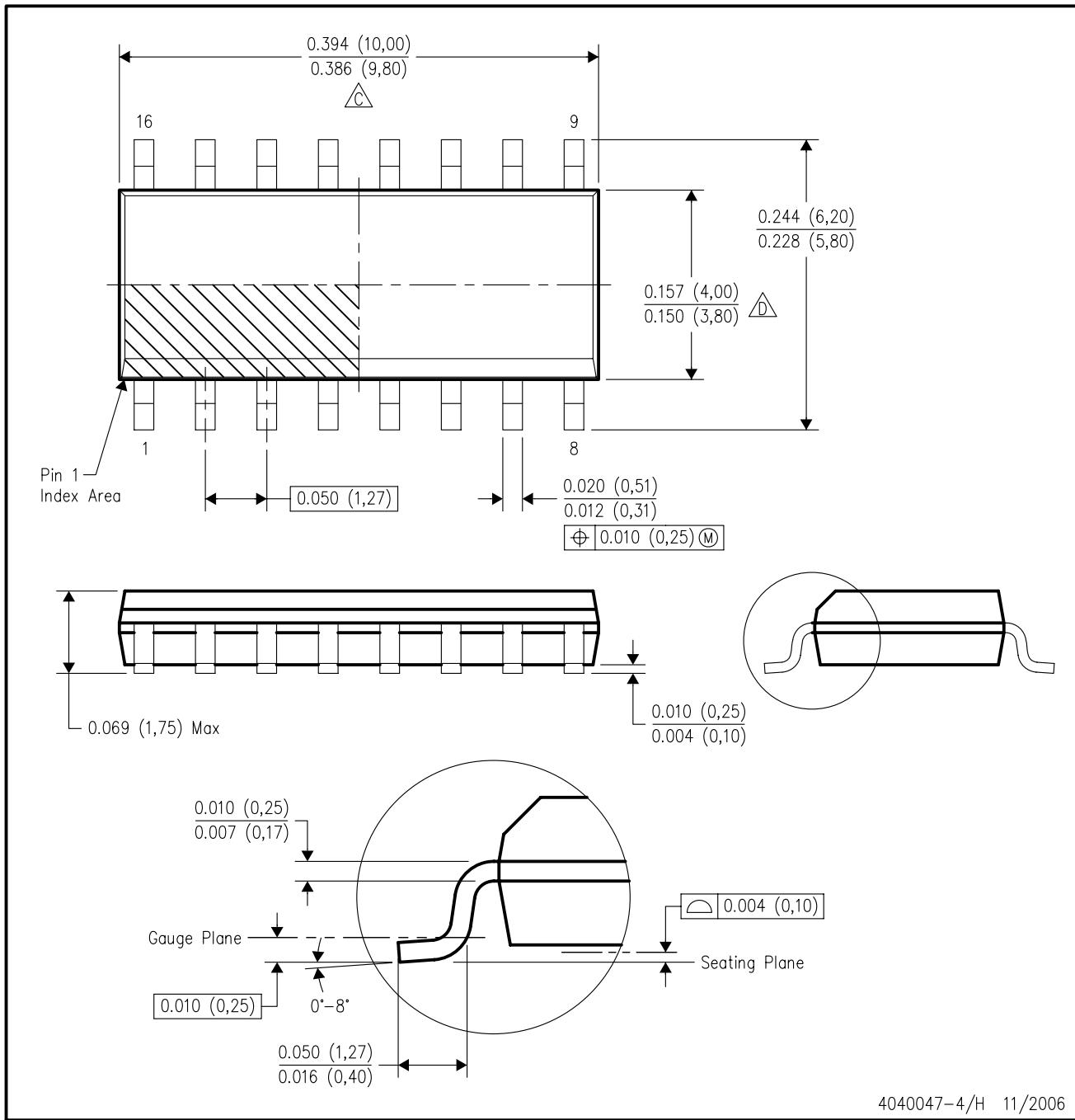
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

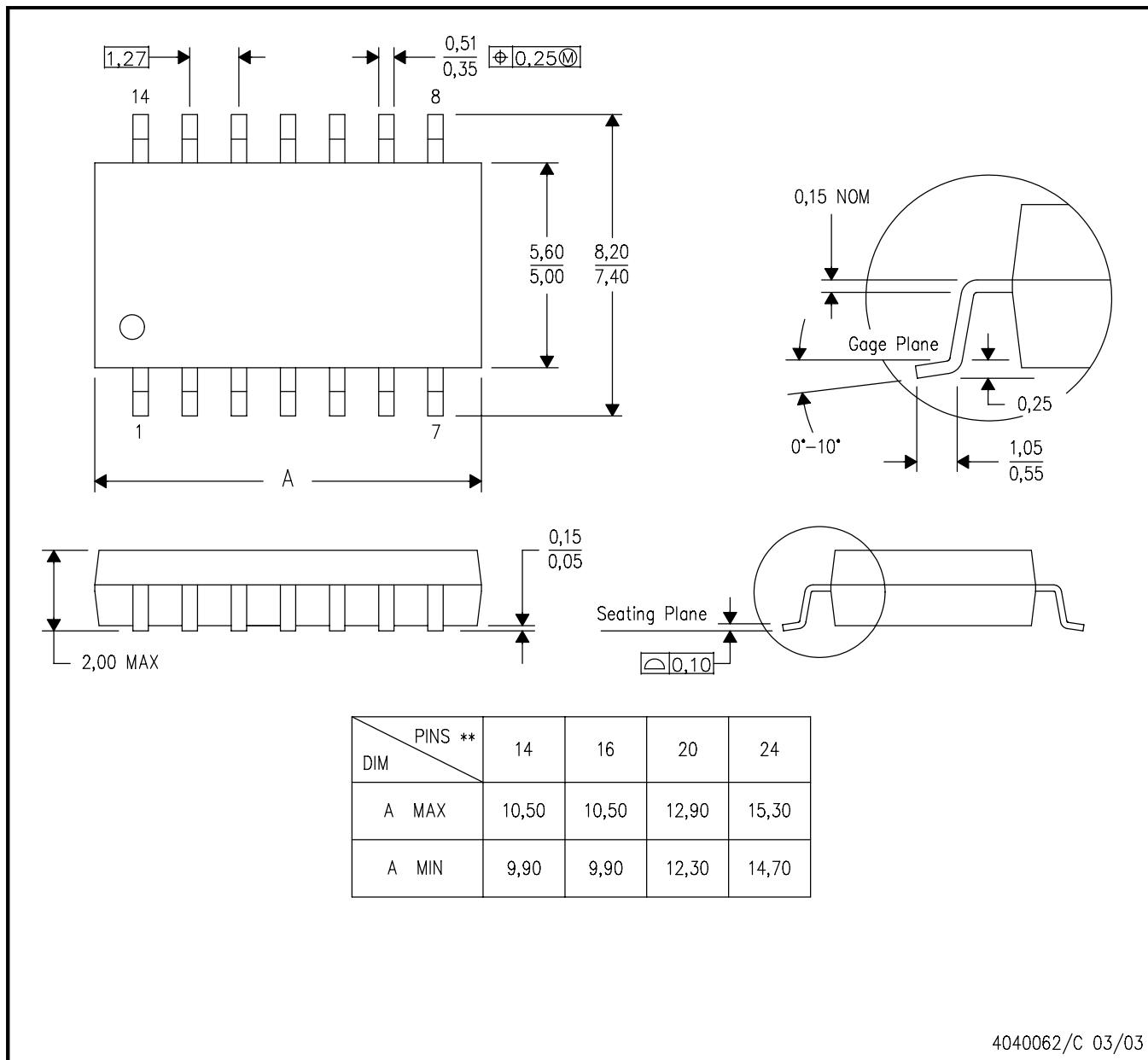
E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

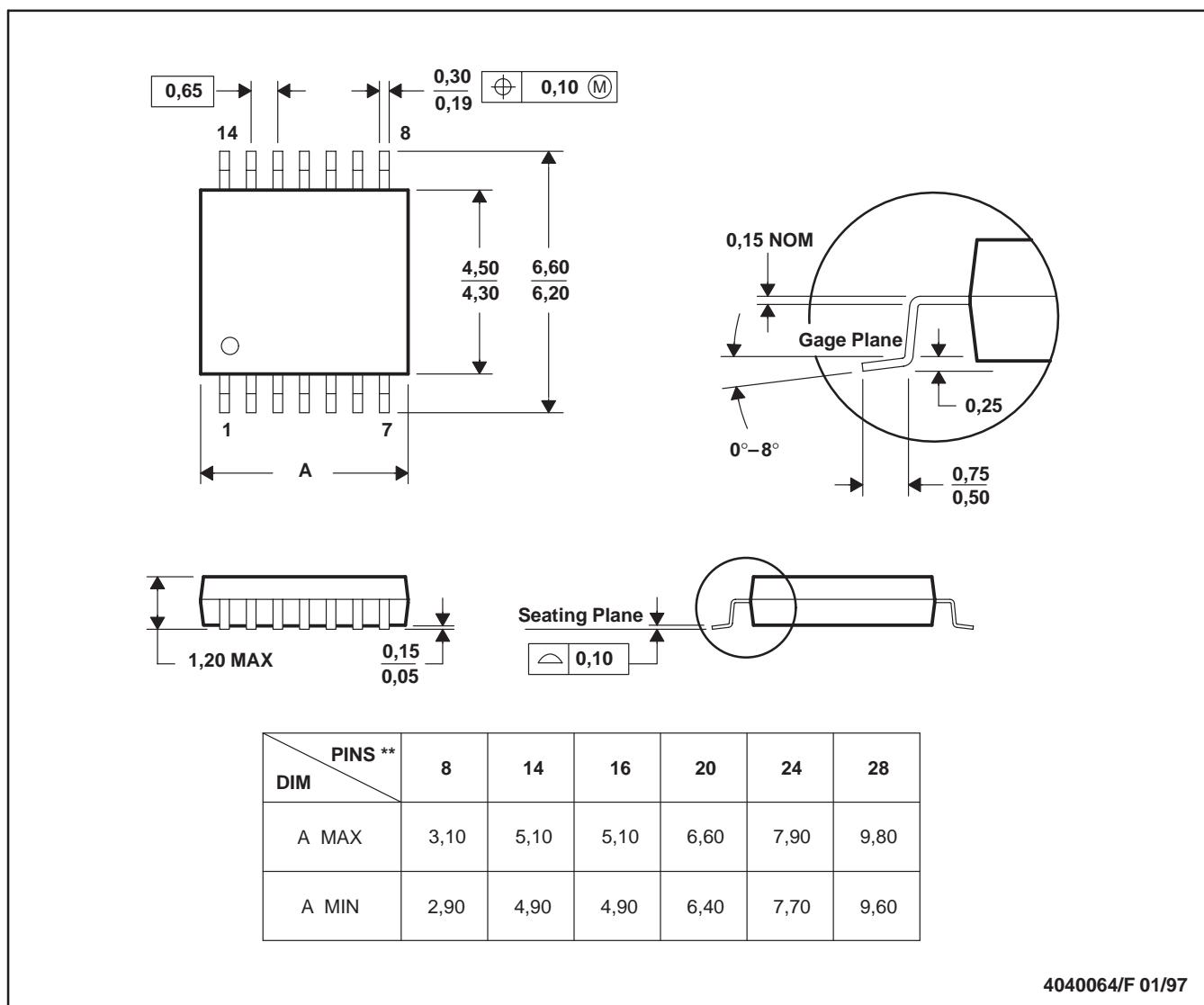


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

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